



This non-electronic component is functionally unaffected by the normal soldering or reflow processes used for semiconductor circuits. The heat resistance time or heat resistance temperature is not applicable for the component.

Thermal Resistance: 8.60

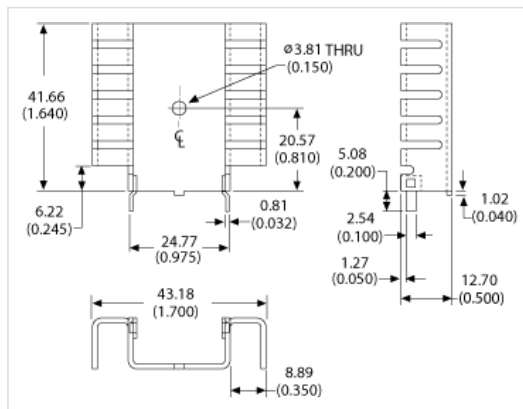


Figure 1 is a schematic diagram showing the typical device mounting dimensions. It includes labels for the Device Centerline, Mounting Surface of Heat Sink, Typical Device Lead Locations, and dimensions X1, Y1, and Ø Z1 (2 Places).

